Package Outline Drawing

Y83.12x11
83 I/O 12mm x 11mm x 5.3mm HDA Module
Rev 0, 3/18

12.00 BSC

Terminal #A1
Index Area

11.00 BSC

⌒ 0.10 C 2X

⌒ 0.10 C 2X

Top View

Seating Plane

C

5.3 Max

⌒ 0.08 C

⌒ 0.10 C

Side View

See Detail A

Datum A

12 11 10 9 8 7 6 5 4 3 2 1

Pin 1 Indicator
C0.25 Ref.

A B C D E F G H J K L

10.0

Datum B

11.0

0.025

Bottom View

△2 1.00

0.20

0.20

R0.100
Ref.

1.00 △2

△3 83x0.60 ±0.05

| ⊕ | 0.10 Ⓜ C A B |
| | 0.05 Ⓜ C |

83x0.60 ±0.05 △3

Detail A

83x 0.60 SQ.

0.200 0.00
0.200
0.200

10.0

0.000

0.300
0.300 0.000

0.000

11.0

Recommended Positive Solder Mask Defined PCB Land Pattern
Top View

83x 0.57 SQ.

0.215 0.000
0.215

10.0

0.000

0.285
0.285 0.000

0.000

11.0

Recommended Solder Stencil
Top View

NOTES:
1. All dimensions are in millimeters.
△2 Represents basic land grid pitch.
△3 These 83 I/O are centered in a fixed row.
   and column matrix at 1.0mm pitch BSC.
4. Dimensioning and tolerancing per ASME Y14.5-2009.